1V 30A off 12Vin 400kHz tested: See Test Report

Parts that change with different Vout:
- R8: frequency setting: 10k for 250kHz, 17.8k for 300kHz, 27.4k for 400kHz, 38.3k for 500kHz, 56.2k for 650kHz, etc. See Table 1 page 18 datasheet
- R18 + R20 + R21 = [Vout / desired step load] minus 5mOhms
- Those caps are on bottom side with max height of 2mm
- Main inductor value should go up for higher Vouts
- Dynamic load resistors will change with Vout
- R9 for Vout setting: R9 = (R6+R7)*0.6V/(Vout - 0.6V)
- VIN 0.6V is "VREF"; R6+R7 is now 20.05kohms

For higher Vouts, use 220uf 6.3V 100V rating ceramic such as C0G22UFR POSCAP
- Those caps are on bottom side with max height of 3mm
- Dynamic load resistors will change with Vout
- R18 = R20 + R21 = [Vout / desired step load] minus 5mOhms

5% duty cycle to keep load from overheating
PCB Number: PMP10364
PCB Rev: A
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